Claims

1. A heat-curing two-component epoxide resin system comprising:

   a first component comprising an epoxide resin; and

   a second component being separately present from the first component,

   characterized in that the second component comprises a homopolymerization catalyst and a reactive diluent,
   wherein a curing agent is not included.

2. The heat-curing two-component epoxide resin system of claim 1, wherein the epoxide resin is selected from the group consisting of a bisphenol-based epoxide resin, a novolac epoxide resin, an aliphatic epoxide resin, a halogenated epoxide resin, and combinations thereof.

3. The heat-curing two-component epoxide resin system of any of the previous claims, wherein the first component comprises a reactive diluent.

4. The heat-curing two-component epoxide resin system of any of the previous claims, wherein the reactive diluent of the first component and/or the reactive diluent of the second component are selected from the group consisting of glycidyl ethers and combinations thereof.

5. The heat-curing two-component epoxide resin system of any of the previous claims, wherein the homopolymerization catalyst is selected from the group consisting of Lewis acids and Lewis bases and combinations thereof.

6. The heat-curing two-component epoxide resin system of any of the previous claims, wherein the first component and/or the second component comprises an ingredient selected from the group consisting of a thermally conductive particle, filler, dye, and combinations thereof.

7. The heat-curing two-component epoxide resin system of any of the previous claims, wherein the first component comprises 30-40 wt.-% of epoxide resin, 5-10 wt.-% of reactive diluent, 40-60 wt.-% of fillers and 0.5-1.5 wt.-% of pigment paste based on 100 wt.-% total weight of the first component.

8. The heat-curing two-component epoxide resin system of any of previous claims, wherein the second component comprises 70-90 wt.-% of reactive diluent and 10-30% wt.-% of homopolymerization catalyst based on 100 wt.-% total weight of the second component.

9. The heat-curing two-component epoxide resin system of any of the previous claims, containing 80 to 98 wt.-% of the first component and 2 to 20 wt.-% of the second component.

10. A use of the heat-curing two-component epoxide resin system of any of the previous claims as a sealing resin, fiber composite component, corrosion protection or adhesive.

11. A mixture for a heat-curing two-component epoxide resin system comprising:
a homopolymerization catalyst, and
a reactive diluent,
wherein a curing agent is not included.

12. The mixture for a heat-curing two-component epoxide resin system of claim 11, containing 10-30% wt.-% of homopolymerization catalyst and 70-90 wt.-% of reactive diluent.